

ABSTRACT

There are provided a gold alloy wire for a bonding wire having high initial bonding ability, high bonding
5 reliability, high roundness of a compression ball, high straightness, high resin flowability resistance, and low specific resistance. The gold alloy wire having high initial bonding ability, high bonding reliability, high roundness of a compression ball, high straightness, high
10 resin flowability resistance, and low specific resistance contains one or more of Pt and Pd of 500 to less than 1000 ppm in total, Ir of 1 to 100 ppm, Ca of more than 30 to 100 ppm, Eu of more than 30 to 100 ppm, Be of 0.1 to 20 ppm, if necessary, one or more of La, Ba, Sr, and Bi of 30 to 100
15 ppm in total, if necessary, and a balance being Au and inevitable impurities.